

# Product Information Sheet

## 1. Objectives

This production information sheet is provided to identify locations of parts, materials, hazardous substances and compound substances in the product that is going to be disposed based on WEEE Directive (2012/19/EU), and to allow waste disposal facilities to dispose the product and to recycle the product in proper manner.

Product: Differential Refractive Index Detector Shodex CD-200 series  
 Product code: F5515010  
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## 2. Disposal

Information of such product as components, major materials, hazardous substances, etc is listed in the next table.

- ★ In order to promote recycling and other ecological activities, components that can be separated and/or disassembled from the product should be listed in this table. Note that the entry of component weight in the table is not essential. ★
- ★ Fill in the column, Remark with such statements as "Remove ○○ sheet before disassembly" and "Perform ○○ processing before disassembly". ★

| Component                   |              | Major material         | Separation process is required or not. | Location where the material is used | How to dispose  | Weight of component (Reference only) | Remark       |
|-----------------------------|--------------|------------------------|--|-------------------------------------|---|--------------------------------------|--------------|
| Category                    | Sub-category |                        |  |                                     |   |                                      |              |
| Switching power supply unit |              | Electrolytic capacitor | ○                                      | Refer to Attached drawing ①.        | Shall be disposed in compliance with Directive 2008/98/EC |                                      | 25mm or more |

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| Component     |               | Major material  | Separation process is required or not. | Location where the material is used | How to dispose  | Weight of component (Reference only) | Remark   |
|---------------|---------------|---|--|-------------------------------------|---|--------------------------------------|--|
| Category      | Sub-category  |   |  |                                     |   |                                      |  |
|               |               | Epoxy glass, and<br>Other electronic component                  | ○                                      | Refer to Attached drawing ①.        | ditto   |                                      | The printed circuit board is greater than 10 cm <sup>2</sup> |
|               |               | Aluminum, Ferrite, Composite, and<br>Other electronic component | ×                                      |                                     | Shall be disposed in landfill after the removal from the body |                                      |  |
| Keyboard Unit | LCD unit      | Liquid crystal material   | ○                                      | Refer to Attached drawing ②.        | Shall be disposed in compliance with Directive 2008/98/EC     |                                      | LCD whose surface area is larger than 100cm <sup>2</sup>     |
|               | Circuit board | Epoxy glass, and<br>Other electronic component                  | ○                                      | Refer to Attached drawing ③.        | ditto   |                                      | The printed circuit board is greater than 10 cm <sup>2</sup> |
|               | Keyboard      | Epoxy glass<br>Other electronic component                       | ○                                      | Refer to Attached drawing ④.        | ditto   |                                      | ditto  |

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| Component |                                  | Major material | Separation process is required or not. | Location where the material is used | How to dispose   | Weight of component<br>(Reference only) | Remark                                     |
|-----------|----------------------------------|----------------|--|-------------------------------------|------------------|---|--|
| Category  | Sub-category                     |                |  |                                     |                  |   |  |
| Cover     |                                  | Iron           | ×                                      |                                     | Material recycle |   | Shall be separated from other parts        |
| Chassis   |                                  |                |  |                                     |                  |   |  |
| Frame     |                                  | Aluminum       | ×                                      |                                     | ditto            |   | ditto                                      |
| Cell unit | Cell block                       | Aluminum       | ×                                      | Refer to Attached drawing ⑤.        | Material recycle |   | Shall remove all of the mounted components |
|           |                                  | Stainless      | ×                                      |                                     | ditto            |   | ditto                                      |
|           | Plastic foam insulating material |                | ×                                      |                                     | Thermal recycle  |   |  |

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| Component             |              | Major material  | Separation process is required or not. | Location where the material is used | How to dispose  | Weight of component (Reference only) | Remark   |
|-----------------------|--------------|---|--|-------------------------------------|---|--------------------------------------|--|
| Category              | Sub-category |   |  |                                     |   |                                      |  |
| Measurement Board     |              | Epoxy glass<br>Other electronic component                       | ○                                      | Refer to Attached drawing ⑥.        | Shall be disposed in compliance with Directive 2008/98/EC     |                                      | The printed circuit board is greater than 10 cm <sup>2</sup> |
| Input/Output board    |              |   |  |                                     |   |                                      |  |
| Power cable           |              | Copper<br>PVC   | ○                                      | Refer to Attached drawings ⑦ and ⑧. | Shall be disposed in compliance with Directive 2008/98/EC     |                                      | External electric cables.                                    |
| Signal cable          |              |   |  |                                     |   |                                      |  |
| Other removable parts |              | Stainless, Optical glass, Epoxy glass, and Electronic component | ×                                      |                                     | Shall be disposed in landfill after the removal from the body |                                      |  |

- 1) The symbol, "○" used in the column "Separation process is required or not" indicates that the part shall be subjected to the process stipulated in WEEE Directive (2012/19/EU) Annex VII. The symbol, "×" is to show that the part shall be subjected to the separation process.
- 2) Location of each component is indicated in Attached drawing-1.
- 3) Remark
  - Part to be processed in accordance with WEEE Annex VII Article 8 (2) is indicated in this Remark column.

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## 3. Record and Report

The followings shall be recorded after receiving and disposing our waste product. In addition, contents of the record shall be reported once a year.

- Number of received waste product and of disposed product
- Client of disposal (Who asked to dispose the product)
- Type/Kind of waste product

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★ Attach drawing and/or photo showing locations where component and/or hazardous substances are used. ★

